Filename: PMP7135RevA - BoM.xls
Date: 4/12/2012

PMP7135RevA - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	100uF	Capacitor, Aluminum, 63V, 10%	0.406 x 0.457 inch	63CV100KX	Sanyo
2	C2, C8	1uF	Capacitor, Ceramic, 50V, X7R, 15%	1206	Std	Std
1	C3	open	Capacitor, Ceramic, 50V, X7R, 15%	1210	Std	Std
1	C4	1uF	Capacitor, Ceramic, 16V, X7R, 15%	603	Std	Std
1	C5	680pF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
1	C6	100pF	Capacitor, Ceramic, 50V, C0G, 5%	603	Std	Std
1	C7	1uF	Capacitor, Ceramic, 16V, X7R, 15%	805	Std	Std
3	C9, C10, C11	100nF	Capacitor, Ceramic, 200V, X7R, 15%	1206	Std	Std
1	D1	STPS1150A	Diode, Schottky, 150V, 1A	SMA	STPS1150A	ST
2	J1, J2	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	L1	82uH	Inductor, SMT, 280mOhm, 3.8A sat, 1.2A rms	0.484 x 0.484 inch	MSD1278-823MLD	Coilcraft
2	P1, P3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	P2, P4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	Q1	Si4848DY	MOSFET, Nch, 150V, 3.5A, 95mOhm	SO8	Si4848DY	Vishay
2	R1, R9	1.00k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	210k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R101	1.00M	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R102	49.9	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R103	100k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R2	19.6k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	8.45k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R4	66.5k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	20.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R6	215k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	open	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	150m	Resistor, Chip,1/2W, 1%	1210	Std	Std
1	SW	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP3	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	LM3481	IC, High Efficiency Low-Side N-Channel Controller	MSOP	LM3481MM	Texas Instruments

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